



<b>Title of Change:</b>	EMC Change for the devices which use Samsung SDI EMC-For SPM3.							
<b>Proposed first ship date:</b>	25 October 2019							
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Xingquan.Fang@onsemi.com>							
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <Xingquan.Fang@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.							
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <Lake.Wang@onsemi.com>							
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>							
<b>Change Part Identification:</b>	The supplier of Mold Compound is changed from Samsung SDI (EMC type is SL7300HW) to Sumitomo (EMC type is E510 Type B).							
<b>Change Category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____							
<b>Change Sub-Category(s):</b>	<div style="display: flex; justify-content: space-between;"> <div> <input type="checkbox"/> Manufacturing Site Addition  <input type="checkbox"/> Manufacturing Site Transfer  <input type="checkbox"/> Manufacturing Process Change         </div> <div> <input checked="" type="checkbox"/> Material Change  <input type="checkbox"/> Product specific change         </div> <div> <input type="checkbox"/> Datasheet/Product Doc change  <input type="checkbox"/> Shipping/Packaging/Marking  <input type="checkbox"/> Other: _____         </div> </div>							
<b>Sites Affected:</b>	ON Semiconductor Sites: ON Suzhou, China	External Foundry/Subcon Sites: None						
<b>Description and Purpose:</b>  The supplier of Mold compound Samsung SDI decided to cease mold compound business from September 1st, 2019.								
<table border="1" style="width: 100%; text-align: center;"> <thead> <tr style="background-color: #92d050;"> <th></th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>SL7300HW; Supplier: Samsung SDI</td> <td>E510 Type B; Supplier: Sumitomo</td> </tr> </tbody> </table>				Before Change Description	After Change Description	Mold Compound	SL7300HW; Supplier: Samsung SDI	E510 Type B; Supplier: Sumitomo
	Before Change Description	After Change Description						
Mold Compound	SL7300HW; Supplier: Samsung SDI	E510 Type B; Supplier: Sumitomo						

**Reliability Data Summary:**

QV DEVICE NAME: FSBS15CH60F

RMS: U56632

PACKAGE: SPM3

Test	Specification	Condition	Interval	Results
HTRB	MILSTD750-1 method M1038A	Tj = 125C for device, bias = 80% of max rated, Vcc-15Vdc, 1000 Hrs	1008 hrs	0/60
TC	JESD22 A104; Q101 appendix 6	-40°C to +125°C	500 cyc	0/60
H3TRB	JESD22-A101	85°C, 85% RH, V=80% rated V or 100V max. 1000 Hours	1008 hrs	0/60
RSH	JESD22 B106	per AEC - Q101	/	0/30

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FCBS0550	FSBS15CH60F
FSBS10CH60L-F166	
FSBS10CH60SL	
FSBS15CH60-F166	
FSBS15CH60L-F166	